



# Bill of Materials

TI DESIGNS

TIPD181: Single-Supply, Electret Microphone Pre-Amplifier Reference Design

Item #	Quantity	Value	Designator	Description	Manufacturer	PartNumber	Supplier Part Number 1
1	4	2.2uF	C1, C3, C5, C6	CAP, TA, 2.2uF, 16V, +/-10%, 5.9 ohm, SMD	Vishay-Sprague	293D225X9016A2TE3	718-1131-1-ND
2	1	10pF	C2	CAP, CERM, 10pF, 50V, +/-5%, C0G/NP0, 0603	AVX	06035A100JAT2A	478-1163-1-ND
3	1	0.1uF	C4	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	AVX	0603YC104JAT2A	478-3726-1-ND
4	1		J1	Header, 100mil, 2x1, Gold, TH	TE Connectivity	5-146261-1	
5	1		J2	RCA Jack, Metal, Right Angle	CUI Inc	RCJ-011	CP-1400-ND
6	1		M1	Electret capsule mic	PUI Audio	POM-3535P-3-R	668-1425-ND
7	1	13.7k	R1	RES, 13.7k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060313K7FKEA	541-13.7KHCT-ND
8	1	75.0k	R2	RES, 75.0k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060375K0FKEA	541-75.0KHCT-ND
9	3	100k	R3, R5, R6	RES, 100k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW0603100KFKEA	541-100KHCT-ND
10	1	49.9	R4	RES, 49.9 ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060349R9FKEA	541-49.9HCT-ND
11	1		U1	36V 10MHz, CMOS Operational Amplifier	Texas Instruments	OPA172IDBVR	OPA172IDBVR-ND

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